

Title (en)

METHOD FOR PRODUCING A CONTACT PIECE, AND CORRESPONDING CONTACT PIECE FOR A VACUUM INTERRUPTER CHAMBER

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES KONTAKTSTÜCKES, SOWIE KONTAKTSTÜCK FÜR EINE VAKUUMSCHALTKAMMER SELBST

Title (fr)

PROCEDE DE FABRICATION D'UN ELEMENT DE CONTACT ET ELEMENT DE CONTACT DESTINE A UNE CHAMBRE DE COMMUTATION A VIDE

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Application

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Abstract (en)

[origin: WO2006079495A1] The invention relates to a method for producing a contact piece, for use in a vacuum interrupter chamber, especially in a low, medium or high voltage vacuum interrupter chamber, according to the preamble of claim 1, and to a contact piece for a medium voltage vacuum interrupter chamber according to the preamble of claim 12. The aim of the invention is to improve multi-layer contact systems in such a manner that even larger layer thicknesses can be used to improve the electrical properties. For this purpose, the contact piece is constituted of at least two layers with a solder film inserted thereinbetween, said layers being welded together in a vacuum furnace in a desired relative position to each other. The two-layer structure can also be achieved by a powder layering process. For this purpose, the powder layers are compressed in a compression mold and then sintered in the furnace to give the finished contact piece blank.

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